## **Electronic Supplementary Information**

A flexible carbonized melamine foam/silicone/epoxy composite pressure sensor

with temperature and voltage-adjusted piezoresistivity for ultrawide pressure

## detection

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**Fig. S1.** a) DSC curve of epoxy; b) compressive strength of epoxy at 23, 40 and 60 °C respectively at the strain rate of 1 mm/min; c) compressive stress-strain curves of epoxy at varied loading cycles; d) compressive stress-strain curves of CMS/silicone/epoxy composites at 23 and 60 °C at the strain rate of 1 mm/min.



**Fig. S2.** Compressive stress-strain curves of CMS/silicone/epoxy composite with 1 (a), 2 (b) and 3 (c) cycle(s) of dip-coating.



**Fig. S3.** Comparison of the mechanical properties of the composite before and after 1 month at 23  $^{\circ}$ C (a), 40  $^{\circ}$ C (b) and 60  $^{\circ}$ C (c).



**Fig. S4.** Sensing performance of the CMS/silicone/epoxy composite sensor. a-b) RCR variation of the CMS/silicone/epoxy composite sensor to 5 (a), 10 (b) and 1000 kPa (c) at 23 °C; d-e) RCR variation of the CMS/silicone/epoxy composite sensor to 250 kPa (d) and 1000 kPa (e) at 40 °C; (f) RCR variation of the CMS/silicone/epoxy composite sensor to 1000 kPa at 60 °C; g-j) RCR variation of the CMS/silicone/epoxy composite sensor to 5 (g), 100 (h), 500 (i) and 1000 kPa (j) at 10 V; k-l) RCR variation of the CMS/silicone/epoxy composite sensor to 1 (k) and 1000 kPa (l) at 15 V.



**Fig. S5**. Effective working pressure ranges of the CMS/silicone/epoxy composite sensor at different temperatures and voltages.



**Fig. S6**. Durability tests for the CMS/silicone/epoxy composite sensor over 2000 cycles of loading-unloading. a) RCR response to 1000 kPa at 23 °C; b) RCR response to 100 and 500 kPa at 60 °C.



**Fig. S7**. Response time of the CMS/silicone/epoxy composite sensor at the voltage of 15 V.

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			Pressure (	kPa*)				
Movement type	Force (N)	Finger (2 cm <sup>2</sup> )	Fist (20 cm <sup>2</sup> )	Foot (250 cm <sup>2</sup> )	Artery of the wrist (0.5 cm <sup>2</sup> )	Refs.		
Pulse	0.75	/	/	/	15	[1]	•	
Poking , Pressing	40-50	200-250	20-25	/	/	[2]		
Griping	370	/	185	/	/	[2]		
Tapping on the screen	2-4	10-20	/	/	/	[3]		
Punching (the lead hand)	1600-2900	/	800-1450	/	/	[4]		
Pushing, Pulling	200-500	/	100-250	/	/	[5]		
Walking	500-1000	/	/	20-40	/	[6]		
Running (downhill and uphill)	700-1800	/	/	28-72	/	[7]		

**Table S1.** Force and the corresponding pressure generated by human motions.

\* The corresponding pressure values were calculated according to the assumed acting area in terms of the forces reported in the references.

<u>Conserve</u>	Lower	Upper	Sensitivity	Refs.	
Sensor	limit (kPa)	limit (kPa)	(kPa <sup>-1</sup> )		
	1.5×10 <sup>-3</sup>	40	14.286 (<0.7	[8]	
			kPa)		
TDMS/ TI/Au			0.032 (0.7-40		
			kPa)		
			0.96 (<50 kPa)		
GO/Laser-Scribed Graphene	0	113	0.005 (50-113	[9]	
			kPa)		
			0.601 (<5 kPa)	[10]	
Ecoflex/CNTs	$0.1 \times 10^{-3}$	130	0.077 (30-130		
			kPa)		
PDMS/PPDL	0	35	44.5 (<100 Pa)	[11]	
PVA/TiaCaT /MXene	2×10 <sup>-3</sup>	250	5.5 (<30 kPa)	[12]	
	210	250	1.5 (30-250 kPa)	[12]	
PVA/Hollow Polyaniline	_	0.1	3.6	[13]	
Spheres-Phytic Acid		0.1	5.0	[10]	
	-		0.023 (<136	[14]	
Chitosan-Poly (hydroxyethyl		3.5×10 <sup>3</sup>	kPa)		
acryla-mide) Double-			0.002 (136-1140		
Network/Na <sub>3</sub> Cit			kPa)		
			0.224×10-3		
			(1140-3230 kPa)		
		3	1.25 (<0.3 kPa)	[15]	
Polyacrylic Acid /Sodium			0.46 (0.3-1.8		
Alginate/CNTs/Ca $^{2+}$	-		kPa)		
			0.07 (1.8-3.0		
			kPa)		
Ecoflex/CIP/CS	70×10-3	330	0.055 (0-2 kPa)	[16]	
Sponge/rGO/polyaniline	-	27	0.152	[17]	
CMS/silicone/epoxy	1	2110	11.5×10 <sup>-2</sup>	Presen	
composite sensor		2110	(0-100 kPa)	t work	

 Table S2. Comparison of the sensing performance of flexible pressure sensors.

 Table S3. Sensitivity of the CMS/silicone/epoxy composite sensor at different

Condition	Sensitivity (kPa <sup>-1</sup> )			
23 °C	2.1×10 <sup>-2</sup>			
40 °C	7.2×10 <sup>-2</sup>			
60 °C	8.8×10 <sup>-2</sup>			
5 V	3.1×10 <sup>-2</sup>			
10 V	8.6×10 <sup>-2</sup>			
15 V	11.5×10 <sup>-2</sup>			

temperatures or voltages in the pressure range of 0 to 100 kPa.

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